



SOM-COMe-CT6-R1000

COM Express® Rel. 3.0 Compact Type 6 module with the AMD Ryzen™ Embedded R1000 family of SoCs

Low-end AMD Ryzen™ on COM Express® Type 6 Compact



HIGHLIGHTS



CPU
AMD Ryzen™ Embedded R1000 processors



GRAPHICS
AMD Radeon™ Vega GPU with 3 Compute Units



CONNECTIVITY
4x USB 3.0; 8x USB 2.0; Up to 5x PCI-e x1; PEG x4 Gen3



MEMORY
Two DDR4 SO-DIMM Slots supporting DDR4-2400 ECC Memory



MAIN FIELDS OF APPLICATION



Coffee &
Vending



Medical



Digital Signage

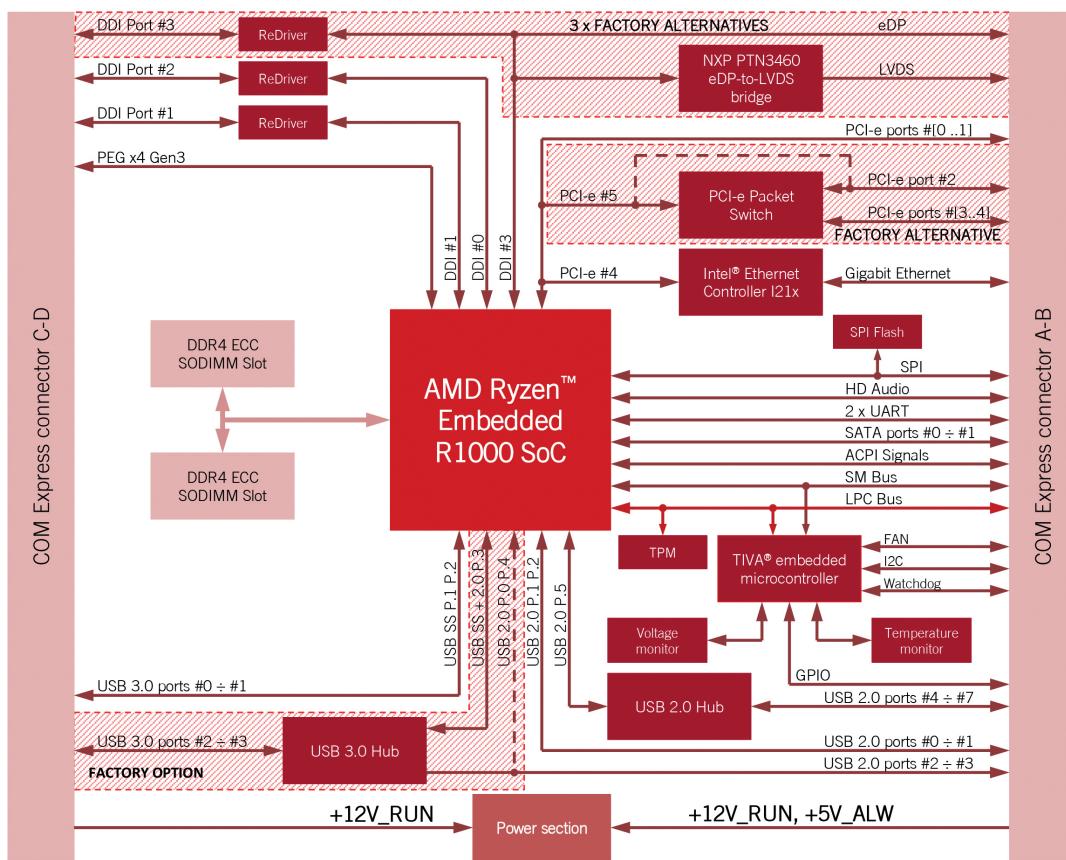
FEATURES

	AMD Ryzen™ Embedded R1606G with GPU AMD Radeon™ Vega 3, Dual Core Four Thread @ 2.6GHz (3.5 Boost), TDP 12-25W		Up to 4 x USB 3.0 Host ports 8 x USB 2.0 Host ports
	AMD Ryzen™ Embedded R1505G with GPU AMD Radeon™ Vega 3, Dual Core Four Thread @ 2.4GHz (3.3 Boost), TDP 12-25W		2 x PCI-e x1 Gen3 lanes Additional 3rd PCI-e x1 Gen3 lane or 3x PCI-e x1 Gen2 lanes (factory alternatives) PCI-express Graphics (PEG) x4
	AMD Ryzen™ Embedded R1305G with GPU AMD Radeon™ Vega 3, Dual Core Four Thread @ 1.5GHz (2.8 Boost), TDP 8-10W		HD Audio interface
	2		2 x UARTs
	Two DDR4 SO-DIMM Slots supporting DDR4-2400 Memory, up to 32GB		SPI, I2C, SM Bus, LPC bus, FAN management Optional TPM 2.0 module on-board 4 x GPIO, 4 x GPO
	AMD Radeon™ Vega 3 GPU with 3 Compute Units DirectX® 12 supported H.265 (10-bit) decode and 8-bit video encode VP9 decode 3 independent displays supported		+12V _{DC} ± 10% and +5V _{SB} (optional)
	Up to 3 x Digital Display Interfaces (DDIs), supporting DP 1.3, DVI and HDMI® 1.4/2.0 eDP or Single/Dual-Channel 18-/24- bit LVDS interface (factory alternatives to third DDI port)		Windows 10 64-bit Linux
	DDIs, eDP up to 4K LVDS up to 1920 x 1200 @ 60Hz		0°C ÷ +60°C (Commercial version)
	2 x S-ATA Gen3 Channels		95 x 95 mm (Com Express® Compact Form factor, Type 6 pinout)
	Gigabit Ethernet interface Intel® I21x family GbE Controller	*Measured at any point of SECO standard heatspreader for this product, during any and all times (including start-up). Actual temperature will widely depend on application, enclosure and/or environment. Upon customer to consider application-specific cooling solutions for the final system to keep the heatspreader temperature in the range indicated.	

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BLOCK DIAGRAM



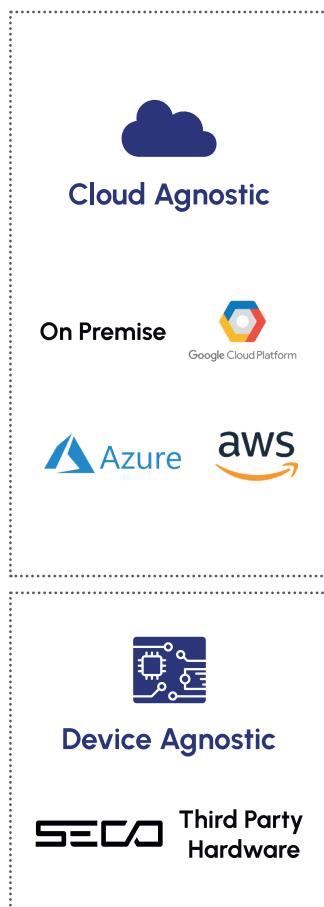
Streamline and expedite your edge computing implementations

EDGEHOG OS

A flexible operating system that adapts to your needs, thanks to the customization tool and Docker support. Reliability and security are built-in through a dual-partition system and native integration with Exein's robust AI-based protection.

DATA ORCHESTRATION

Integrate third-party services, simplify data flows and analysis, and enhance business efficiency by enabling easy and fast utilization of AI.



DEVICE MANAGER

Update, configure, and manage remote devices. Optimize time and costs to maximize operational efficiency and security without the need for costly field interventions.

PORTAL

Analyze data from remote devices, customize the user experience with applications tailored to user needs, and manage user rights, company access, and tenant privileges.

SERVICES

Custom Apps



Device Manager

»Edgehog

Data Orchestration

»Astarte

Portal

EDGEHOG OS

Containers

SDK



Double Partition

Device Manager Agent

Incremental Updates

Immutable OS

Scan to know more about our solution

EDGEHOG OS



CLEA DOCS

